



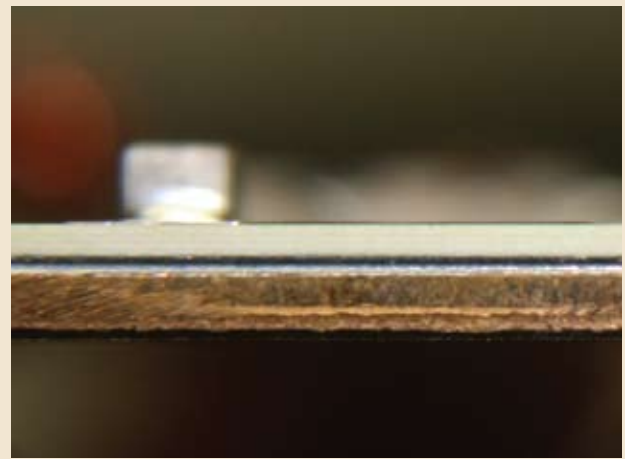
Ground Plane Solder Bonding For High Power Circuit Boards

Driven to find a better way to dissipate heat created by the increase in power requirements, Custom Assembly has developed a more efficient way to solder boards. Using a single-pass reflow solder process, Custom Assembly can bond copper plate ground planes and components all at once, saving time and reducing costs.

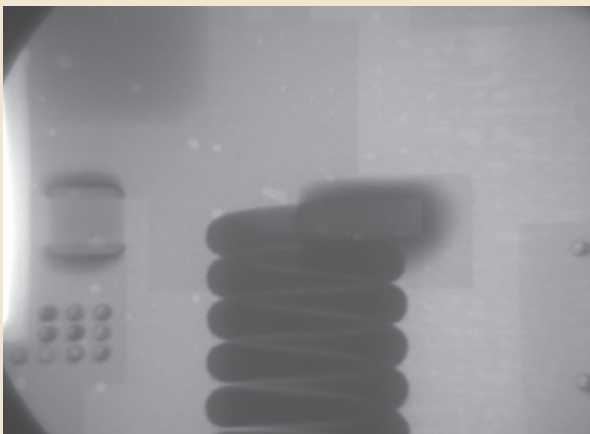
- **Minimal solder voids**
- **Quick and efficient single-pass process**
- **Ability to accommodate low-volume production runs**
- **Cost effective solution**



Special fixtures allow for a single reflow process.



Excellent thermal and electrical bond.



X-ray analysis confirms minimal solder voids between the PCB and copper plates.



Please contact our application engineering department to review your high power design requirements.

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